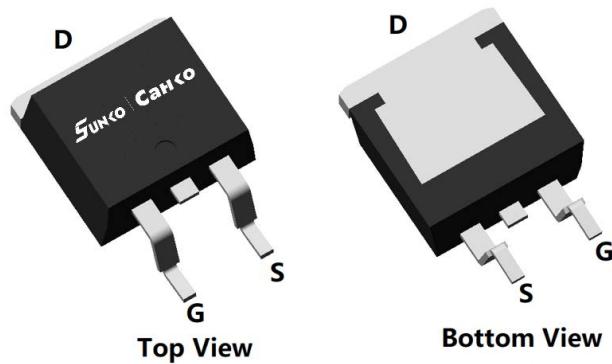
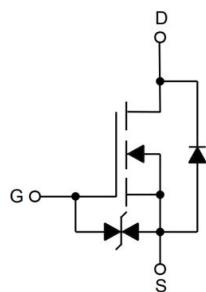


N-Channel Enhancement Mode Field Effect Transistor



TO-263



Product Summary

- V_{DS} 60V
- I_D 200A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <2.9 mohm
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Consumer electronic power supply
- Isolated DC-DC Converters
- Motor control
- Invertors

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current ^A	$T_A=25^\circ\text{C}$	I_D	25	A
	$T_A=100^\circ\text{C}$		15	
	$T_c=25^\circ\text{C}$		200	
	$T_c=100^\circ\text{C}$		125	
Pulsed Drain Current ^B		I_{DM}	600	A
Avalanche energy ^C		E_{AS}	500	mJ
Total Power Dissipation ^D	$T_A=25^\circ\text{C}$	P_D	4.4	W
	$T_A=100^\circ\text{C}$		1.7	
	$T_c=25^\circ\text{C}$		260	
	$T_c=100^\circ\text{C}$		104	
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	0.48	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Ambient ^E		$R_{\theta JA}$	28	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	°C

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCB200G06B	F2	SCB200G06B	800	/	8000	13" reel

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
		$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}, T_J=150^\circ\text{C}$			100	
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	2.8	4.0	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$		2.3	2.9	$\text{m}\Omega$
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$			1.2	V
Gate resistance	R_{G}	$f=1\text{MHz}$	-	2.3	-	Ω
Maximum Body-Diode Continuous Current	I_{S}				200	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=100\text{KHZ}$		4165		pF
Output Capacitance	C_{oss}			900		
Reverse Transfer Capacitance	C_{rss}			59		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=50\text{A}$		65		nC
Gate-Source Charge	Q_{gs}			11.9		
Gate-Drain Charge	Q_{gd}			9.8		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=25\text{A}, dI/dt=100\text{A/us}$		63		ns
Reverse Recovery Time	t_{rr}			58		
Turn-on Delay Time	$t_{\text{d(on)}}$			22.5		
Turn-on Rise Time	t_{r}	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=30\text{V}, I_{\text{D}}=25\text{A}$ $R_{\text{GEN}}=2\Omega$		6.7		ns
Turn-off Delay Time	$t_{\text{d(off)}}$			80.3		
Turn-off fall Time	t_{f}			26.9		

Note:

- A. The maximum current rating is package limited.
- B. Repetitive rating; pulse width limited by max. junction temperature.
- C. $V_{\text{DD}}=50\text{ V}$, $R_{\text{G}}=25\ \Omega$, $L=0.5\text{mH}$, starting $T_J=25\ ^\circ\text{C}$.
- D. P_{D} is based on max. junction temperature, using junction-case thermal resistance.
- E. The value of $R_{\theta\text{JA}}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\ ^\circ\text{C}$.

■ Typical Performance Characteristics

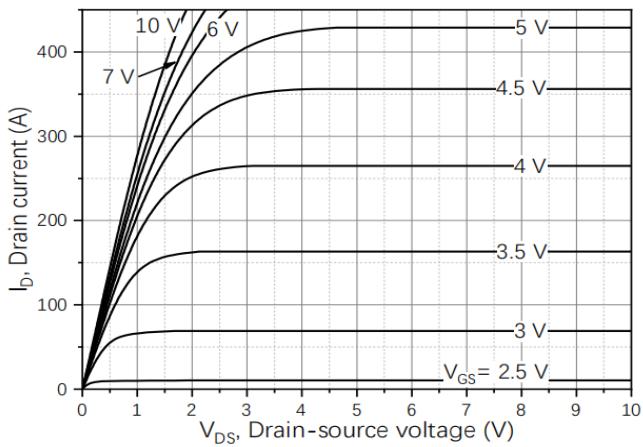


Figure1. Output Characteristics

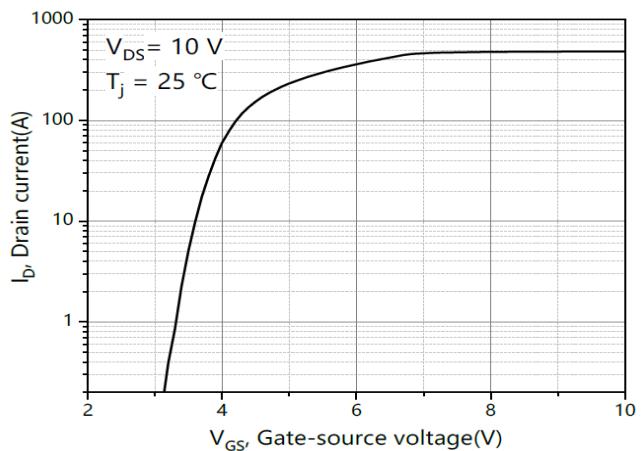


Figure2. Transfer Characteristics

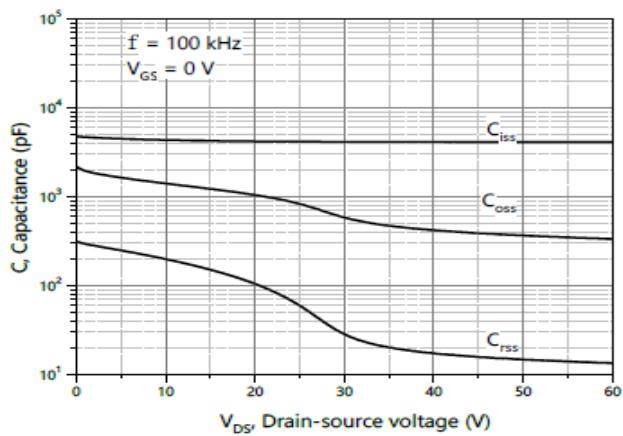


Figure3. Capacitance Characteristics

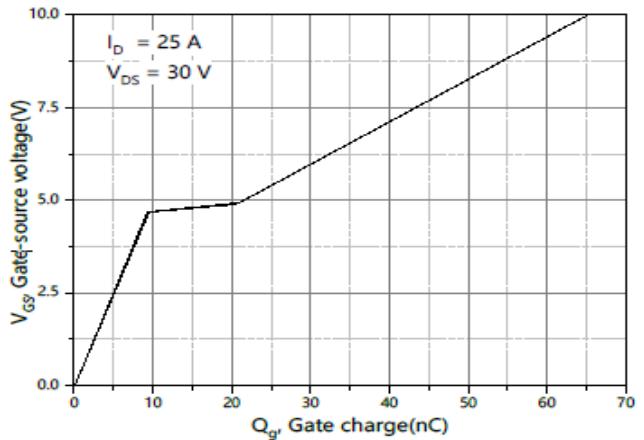


Figure4. Gate Charge

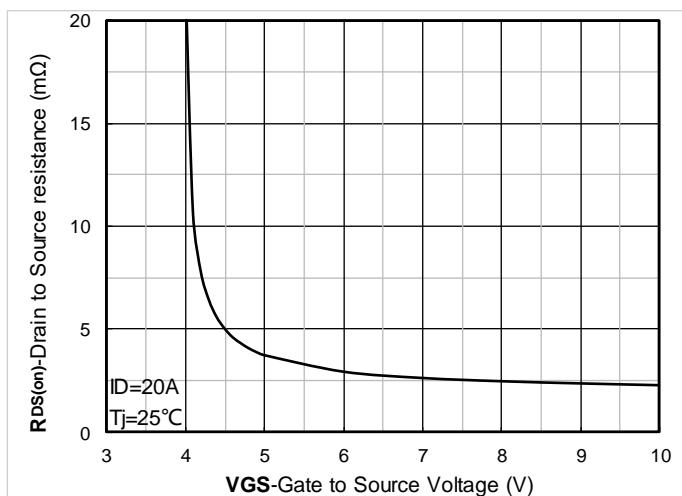


Figure 5. On-Resistance vs Gate to Source Voltage

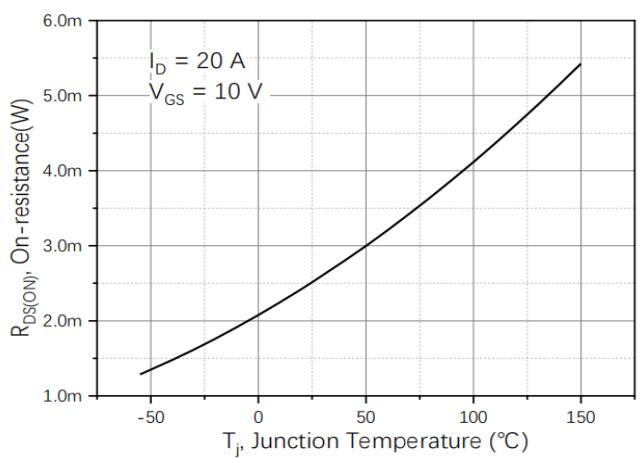


Figure 6. Drain-Source on Resistance

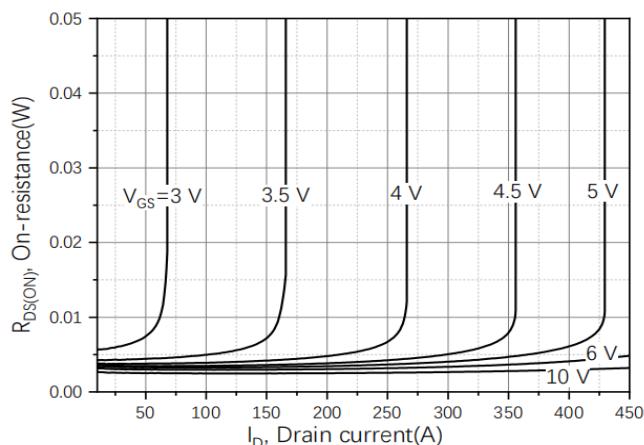


Figure 7. Drain-Source on Resistance

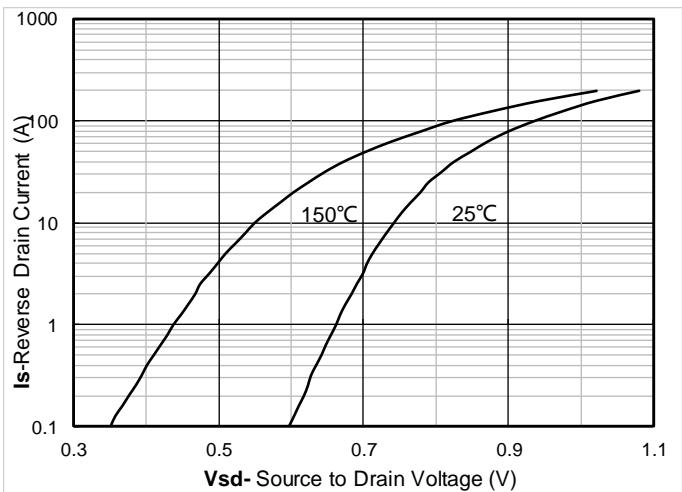


Figure 8. Forward characteristics of reverse diode

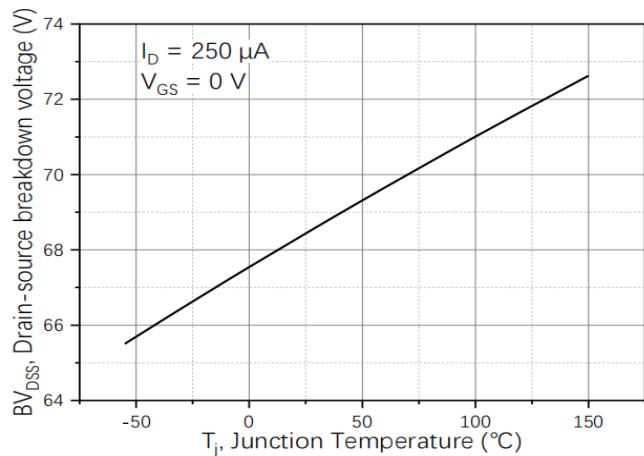


Figure 9. Drain-source breakdown voltage

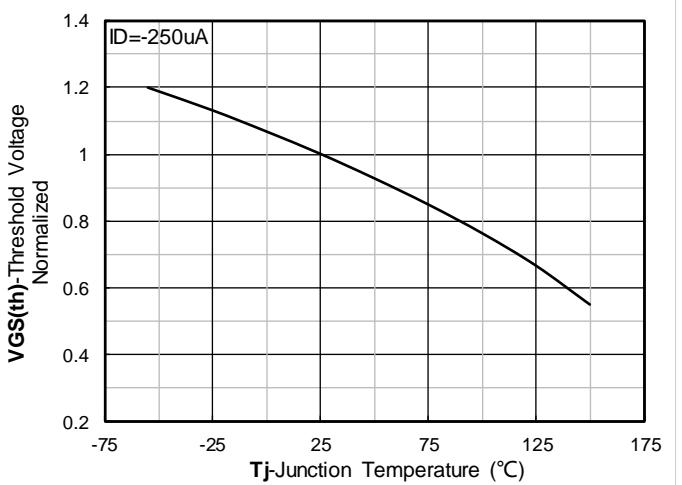


Figure 10. Normalized Threshold voltage

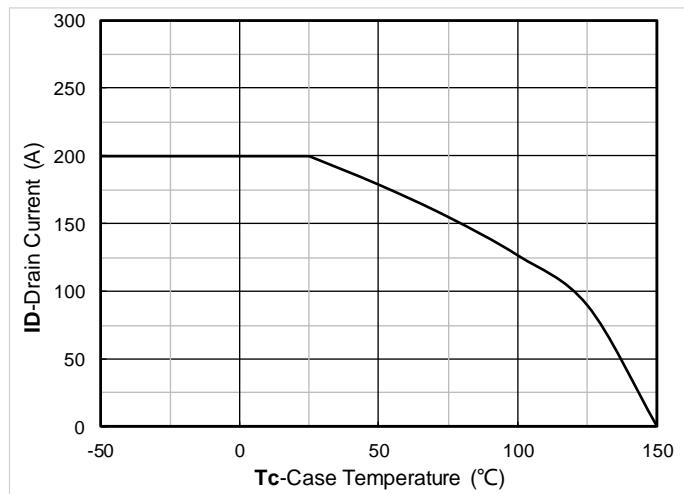


Figure 11. Current dissipation

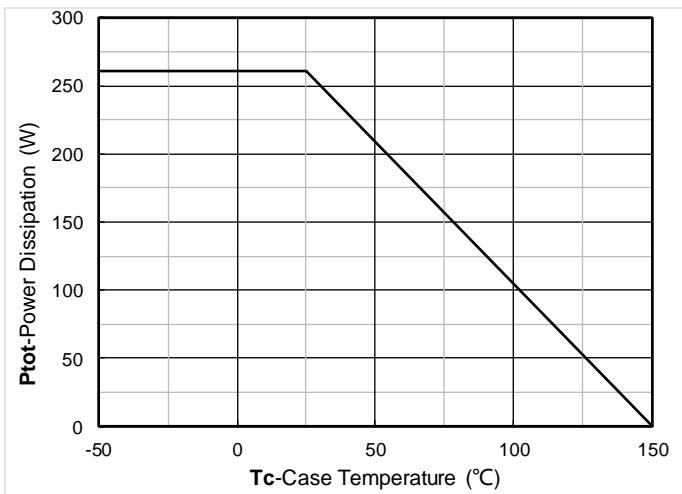


Figure 12. Power dissipation

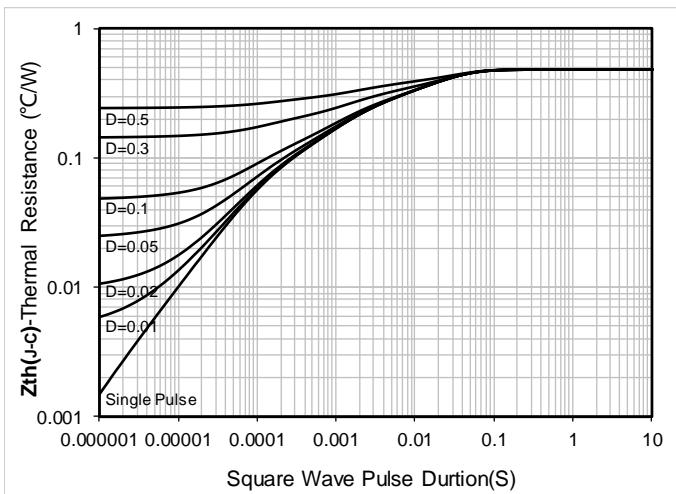


Figure 13. Maximum Transient Thermal Impedance

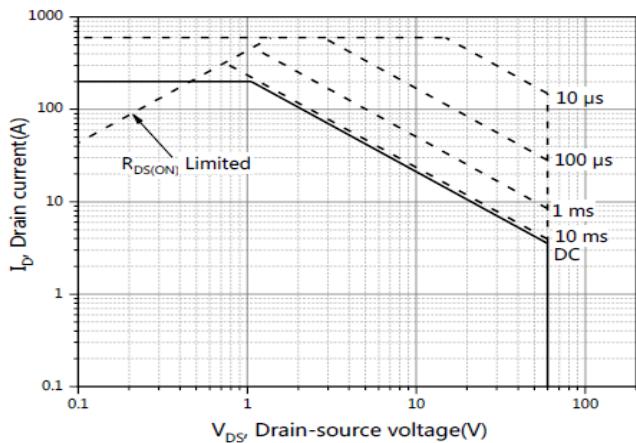


Figure 14. Safe Operation Area

■ Test circuits and waveforms

Figure A: Gate Charge Test Circuit & Waveforms

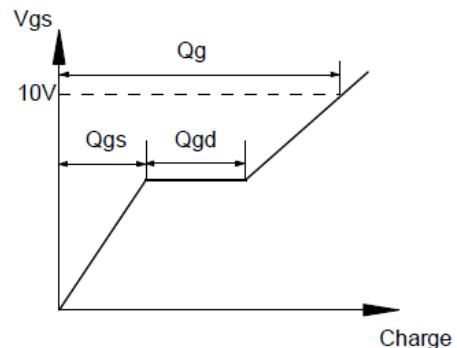
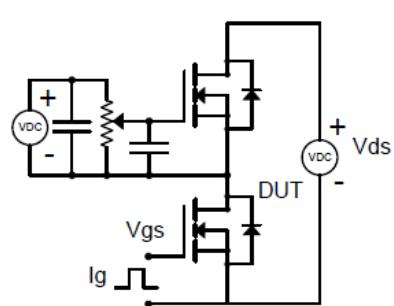


Figure B: Resistive Switching Test Circuit & Waveforms

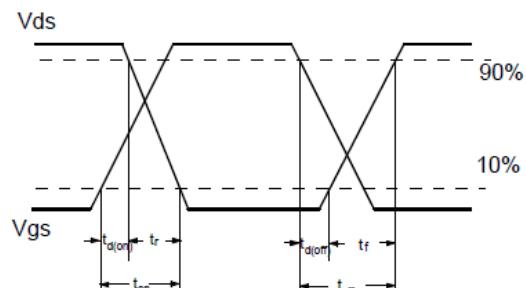
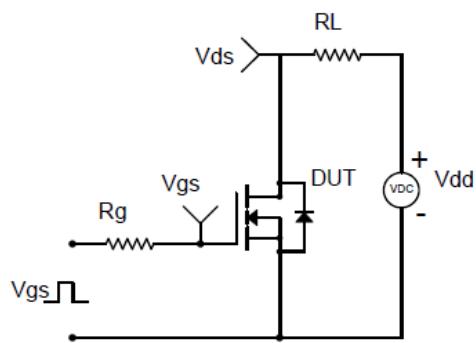


Figure C: Unclamped Inductive Switching (UIS) Test

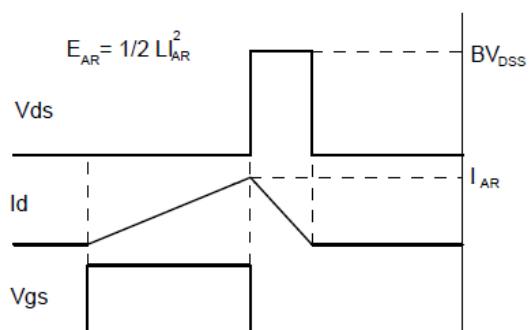
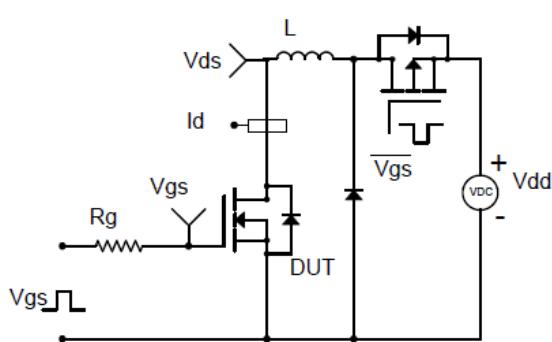
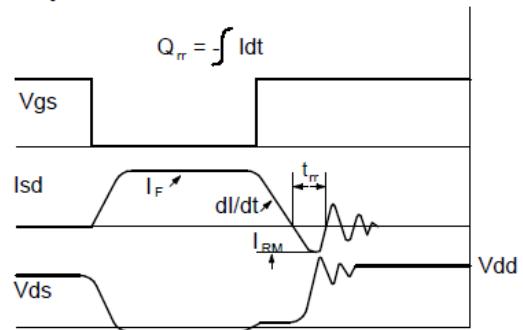
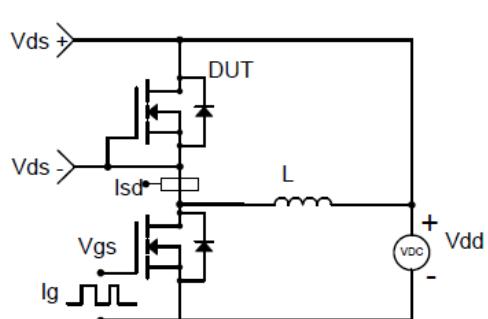
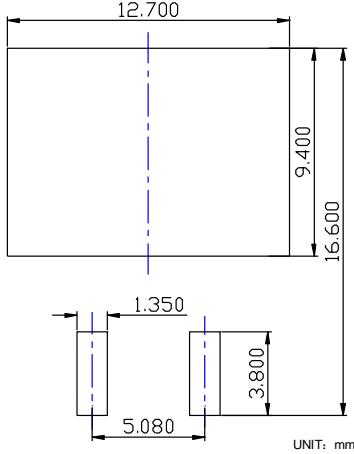
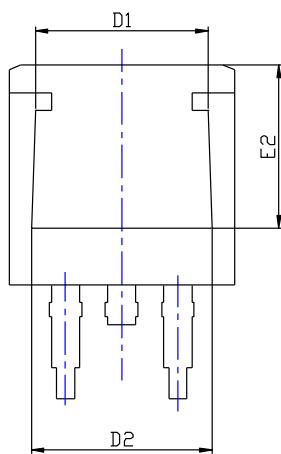
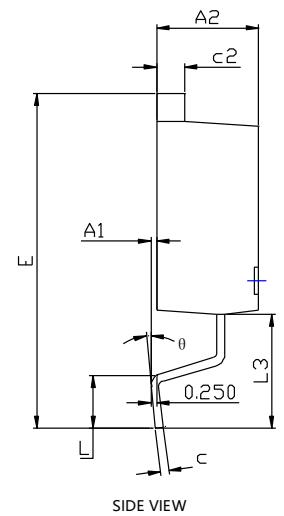
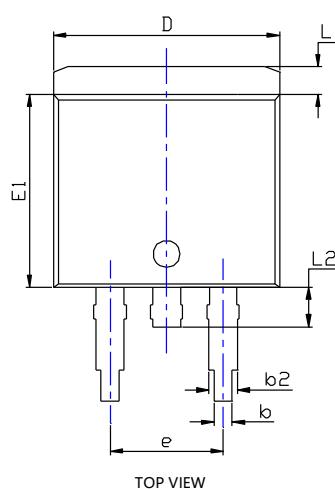


Figure D: Diode Recovery Test Circuit & Waveforms



■ TO-263-HY Package information



SYMBOL	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A1	0.000	---	0.010	0.000	---	0.250
A2	0.174	0.180	0.186	4.430	4.580	4.730
b	0.028	0.032	0.036	0.720	0.820	0.920
b2	0.046	0.050	0.054	1.180	1.280	1.380
c	0.013	0.015	0.018	0.330	0.390	0.450
c2	0.048	0.050	0.053	1.220	1.280	1.340
D	0.394	0.400	0.406	10.000	10.150	10.300
D1	0.295	0.307	0.319	7.500	7.800	8.100
D2	0.303	0.315	0.327	7.700	8.000	8.300
E	0.571	0.591	0.610	14.500	15.000	15.500
E1	0.337	0.341	0.348	8.550	8.700	8.850
E2	0.276	0.287	0.299	7.000	7.300	7.600
e	0.200BSC			5.080BSC		
L	0.070	---	0.110	1.790	---	2.790
L1	0.044	---	0.056	1.120	---	1.420
L2	0.030	---	0.070	0.770	---	1.770
L3	0.197REF			5.000REF		
θ	0°	---	8°	0°	---	8°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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